



U□38□4X Series

Single Color ϕ 3 Flush Mount Round Shape Type

Features

Package	ϕ 3 Round shape type, UB,UC,UG : Water Clear epoxy UY : Pale Yellow Clear epoxy UR : Pale Red Clear epoxy
Product features	• Outer Dimension ϕ 3 Round shape type • Operation temperature range. Storage Temperature : -40°C~100°C Operating Temperature : -40°C~85°C • Lead-free soldering compatible • RoHS compliant
Dominant wavelength	Blue : 470nm (UB) Blue Green : 505nm (UC) Green : 525nm (UG) Yellow : 590nm (UY) Red : 626nm (UR)
Half Intensity Angle	UB,UC,UG : 56 deg. UY,UR : 66 deg.
Die materials	UB,UC,UG : InGaN, UY,UR : AlGaInP
Rank grouping parameter	Sorted by luminous intensity per rank taping
Soldering methods	TTW (Through The Wave) soldering and manual soldering
ESD	InGaN : Less than 1kV(HBM), AlGaInP : More than 2kV(HBM)
Packing	Bulk : 200pcs(MIN.)

Recommended Applications

Amusement Equipment, Electric Household Appliances, OA/FA, Other General Applications

Color and Luminous Intensity

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color		Dominant Wavelength λ_d (nm)		Luminous Intensity I_v (mcd)		
					TYP.	I_F	MIN.	TYP.	I_F
UB3804X	InGaN	Blue	Water Clear Clear		470	20	240	672	20
UC3804X	InGaN	Blue Green			505	20	672	2,688	20
UG3804X	InGaN	Green			525	20	960	2,688	20
UY3864X	AlGaInP	Yellow			590	20	250	500	20
UR3864X	AlGaInP	Red			630	20	220	440	20

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings					Unit
		UB	UC	UG	UY	UR	
Power Dissipation	P_d	105	105	105	150	150	mW
Forward Current	I_F	25	25	25	50	50	mA
Pulse Forward Current ※1	I_{FRM}	60	60	60	100	100	mA
Derating (Ta=25°C or higher)	ΔI_F	0.33	0.33	0.33	0.67	0.67	mA/°C
Reverse Voltage	V_R	5	5	5	5	5	V
Operating Temperature	T_{opr}	-40~+85					°C
Storage Temperature	T_{stg}	-40~+100					°C

※1 I_{FRM} Measurement condition : Pulse Width $\leq 1ms$, Duty $\leq 1/20$.

Electro-Optical Characteristics

(Ta=25°C)

Item	Conditions	Symbol	Characteristics						Unit
				UB	UC	UG	UY	UR	
Forward Voltage	I _F =20mA	V _F	TYP.	3.7	3.7	3.7	2.2	2.2	V
			MAX.	4.2	4.2	4.2	2.8	2.8	
Reverse Current	V _R =5V	I _R	MAX.	100	100	100	100	100	μ A
Peak Wavelength	I _F =20mA	λ _p	TYP.	465	502	517	592	641	nm
Dominant Wavelength	I _F =20mA	λ _d	TYP.	470	505	525	590	630	nm
Spectral Line Half Width	I _F =20mA	Δλ	TYP.	26	30	35	18	18	nm
Half Intensity Angle	I _F =20mA	2θ 1/2	TYP.	56	56	56	66	66	deg.

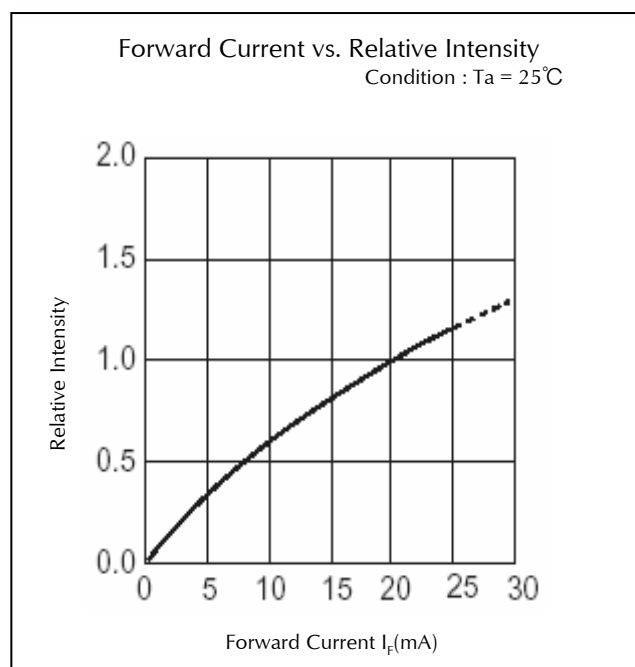
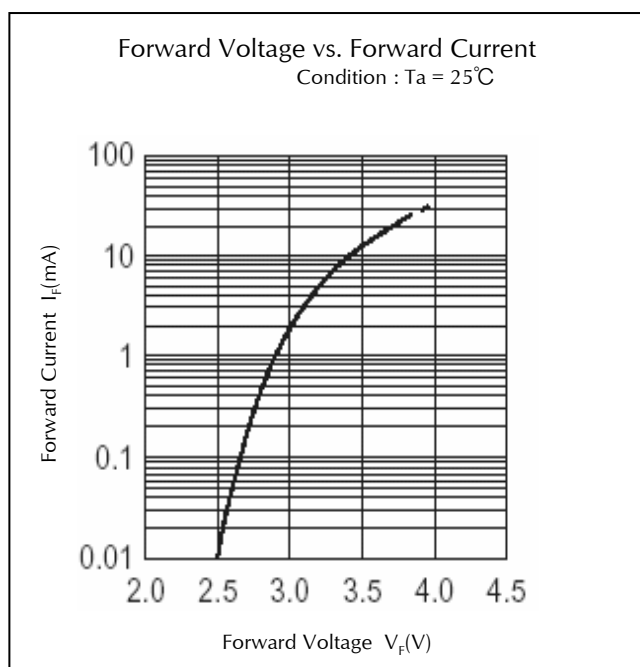
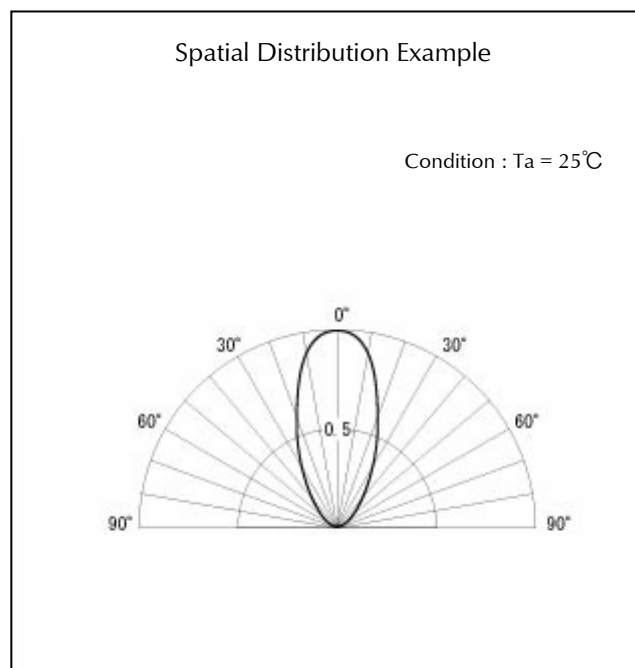
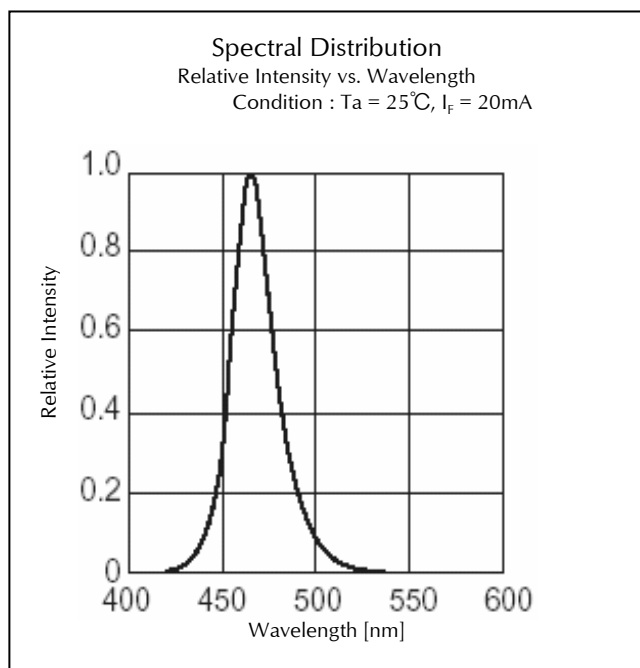
Luminous Intensity Rank

(Ta=25°C)

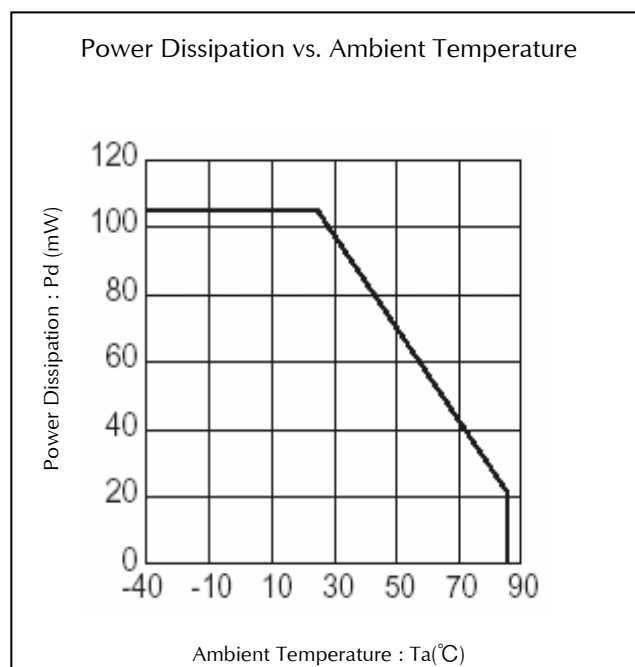
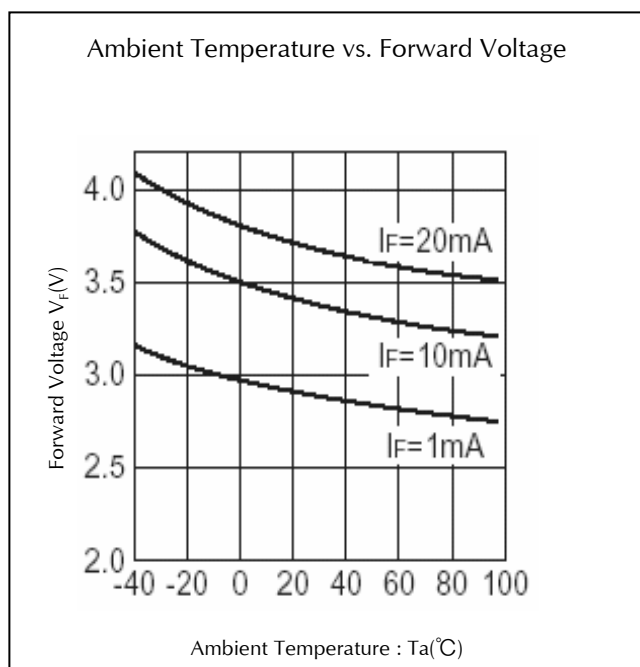
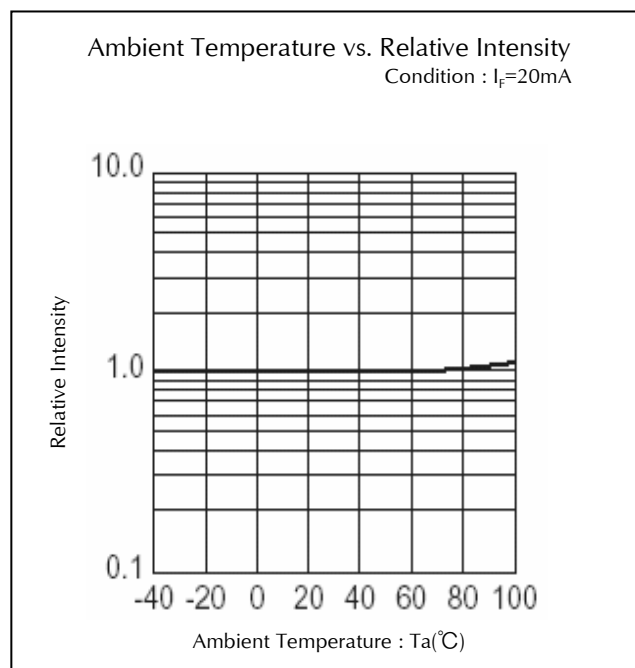
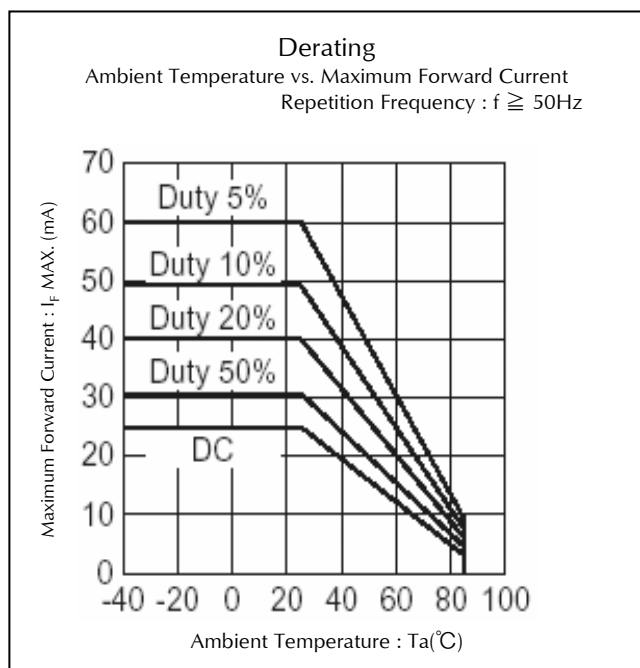
Rank	I _V (mcd)										Condition
	UB		UC		UG		UY		UR		
	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
A			672	1,344			250	500	220	440	I _F = 20mA
B			960	1,920			350	700	300	600	
C	240	480	1,344	2,688	960	1,920	500	1,000	440	880	
D	336	672	1,920	3,840	1,344	2,688	700	1,400	600	1,200	
E	480	960	2,688	5,376	1,920	3,840	1,000	2,000	880	1,760	
F	672	1,344	3,840	-	2,688	5,376	1,400	-	1,200	-	
G	960	1,920			3,840	7,680					
H	1,344	-			5,376	-					

※Please contact our sales staff concerning rank designation of UY and UR.

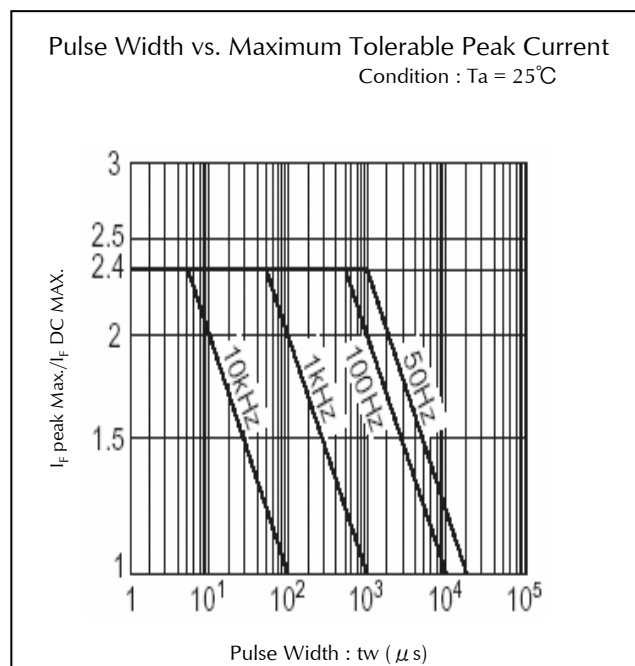
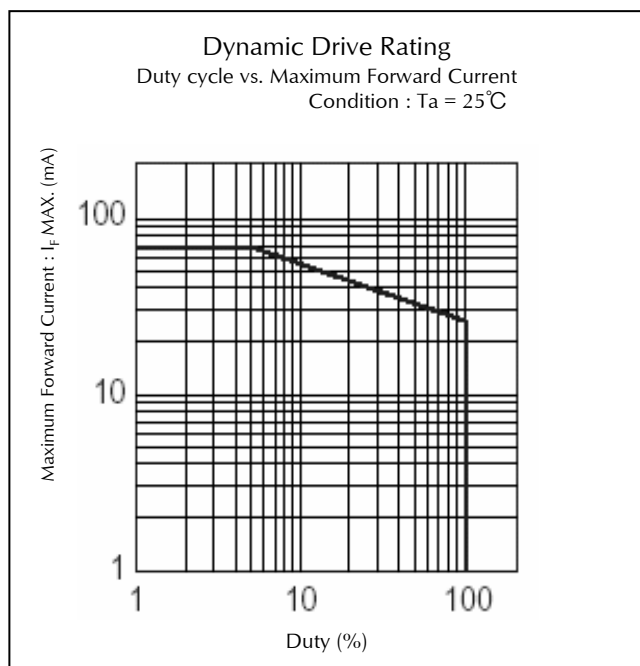
Technical Data(UB)



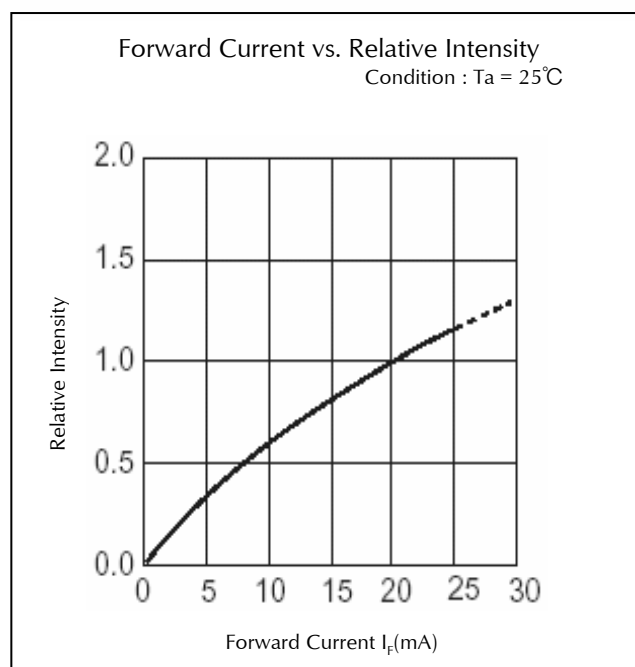
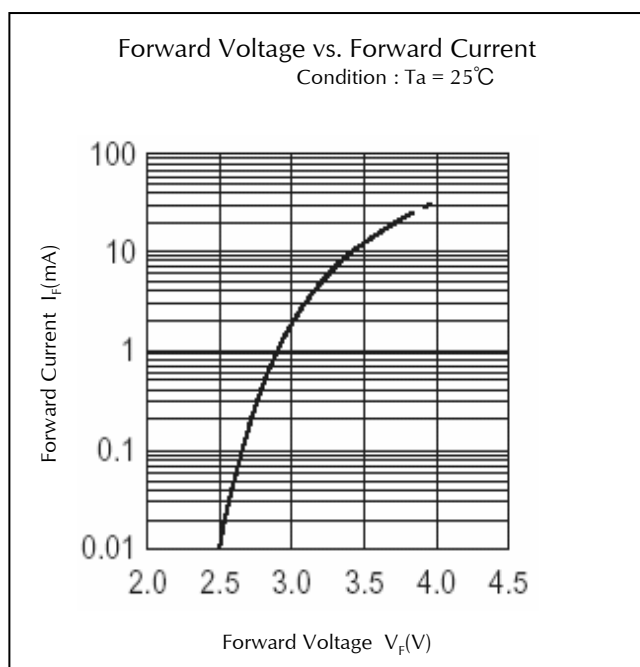
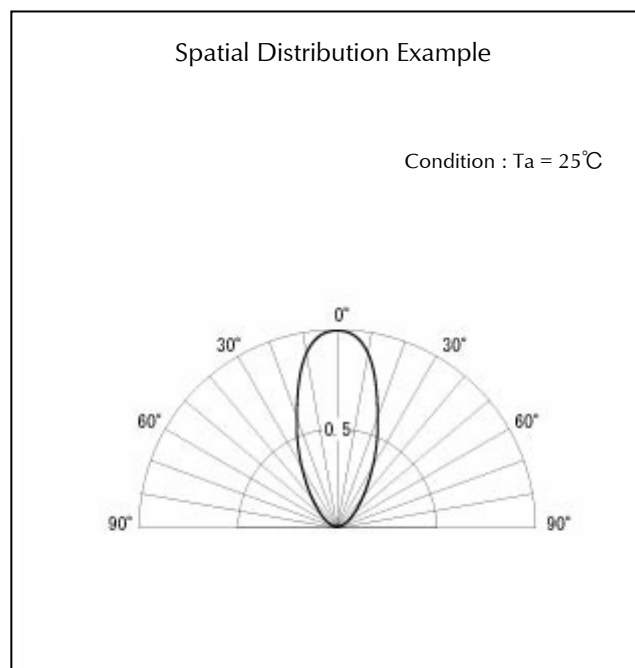
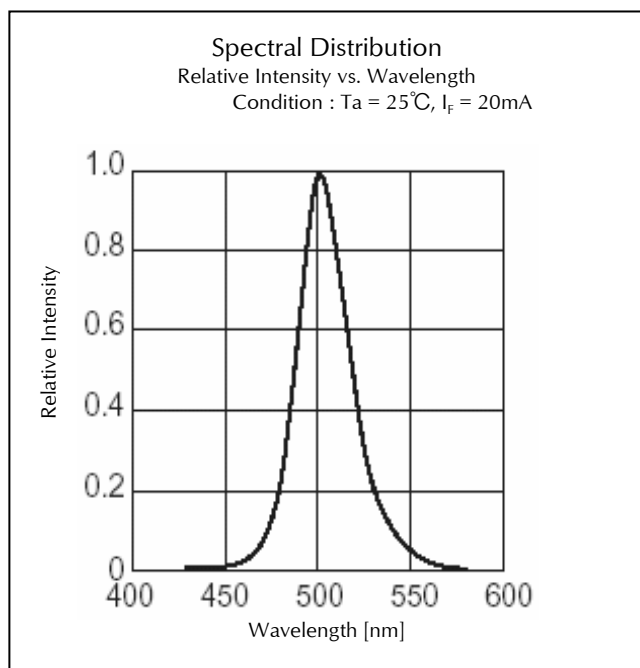
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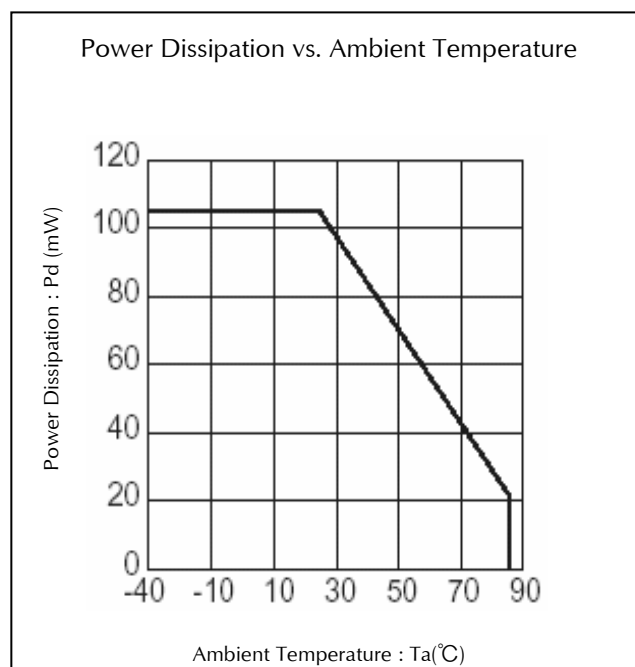
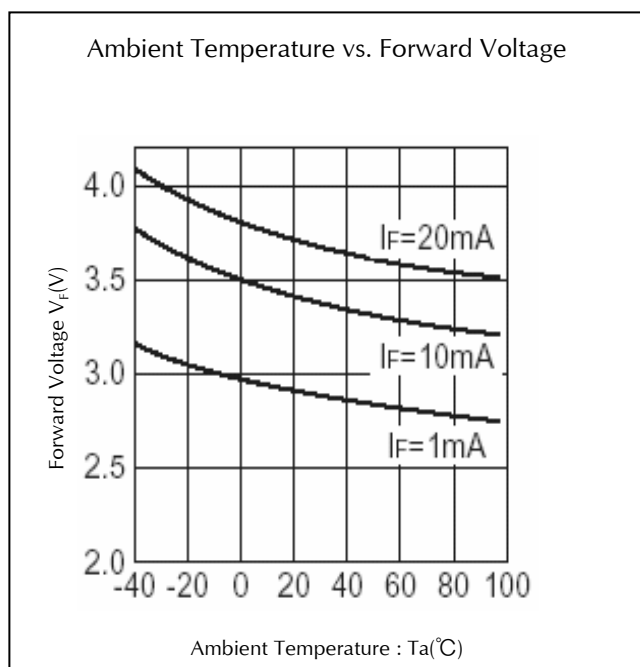
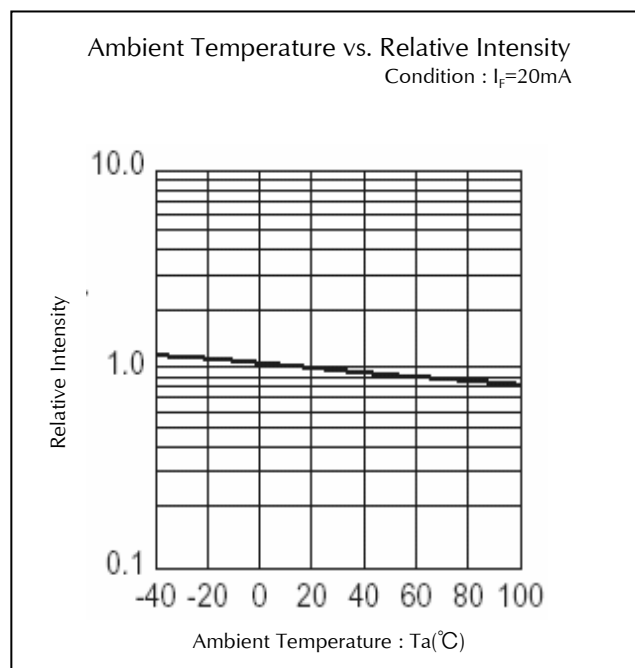
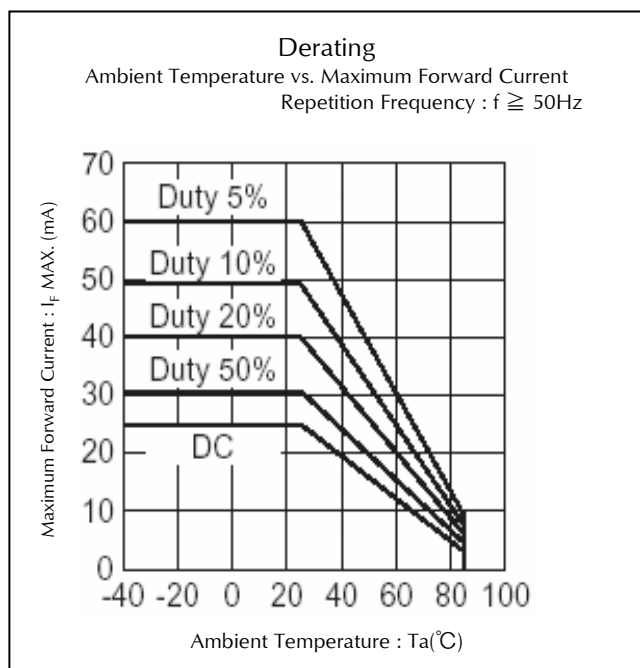
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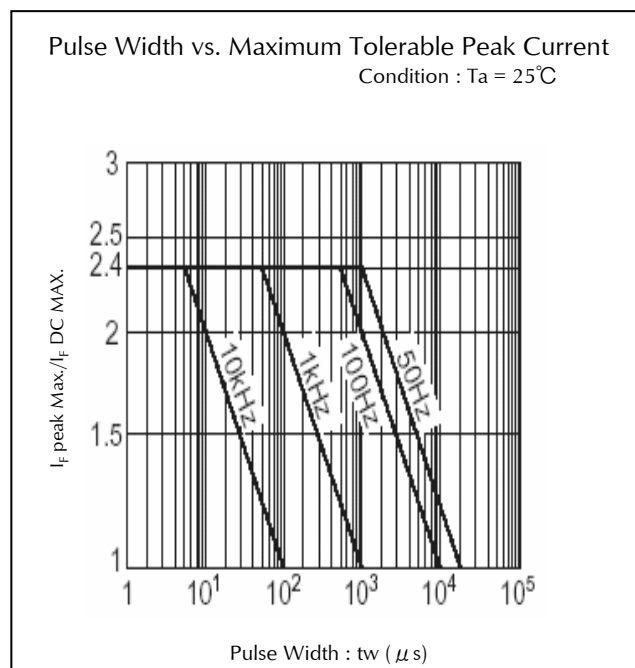
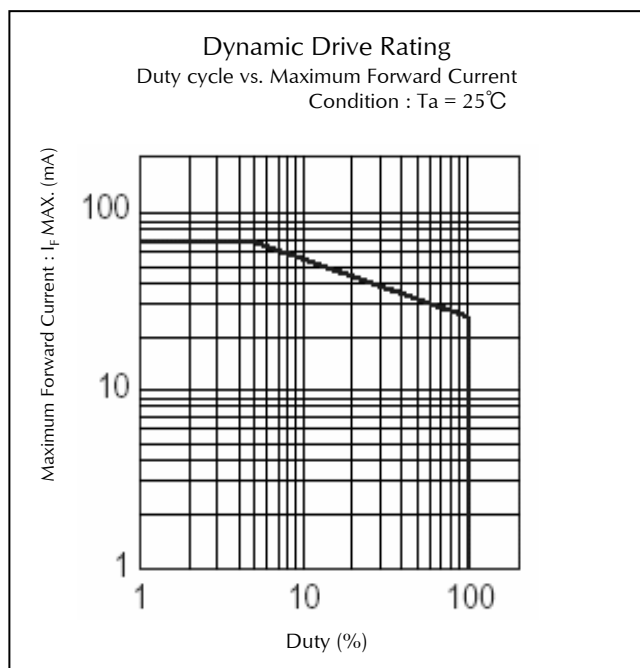
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Technical Data(UC)

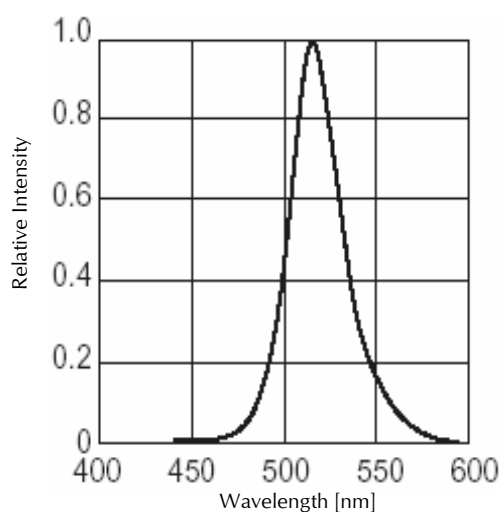


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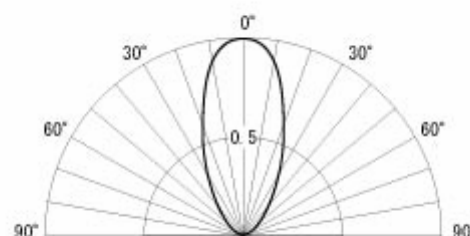
Technical Data(UG)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

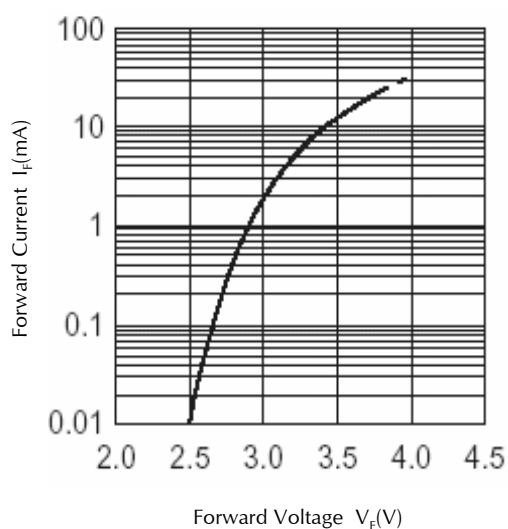


Spatial Distribution Example

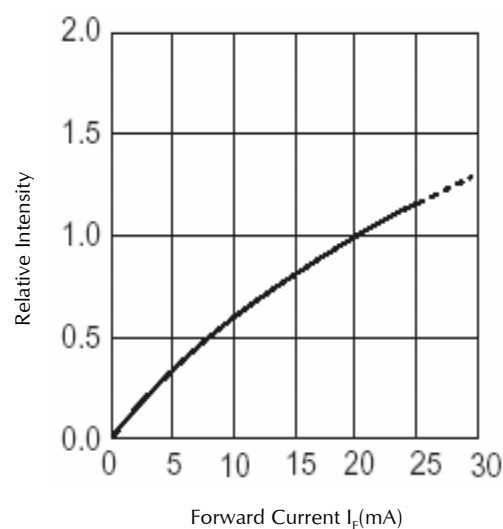
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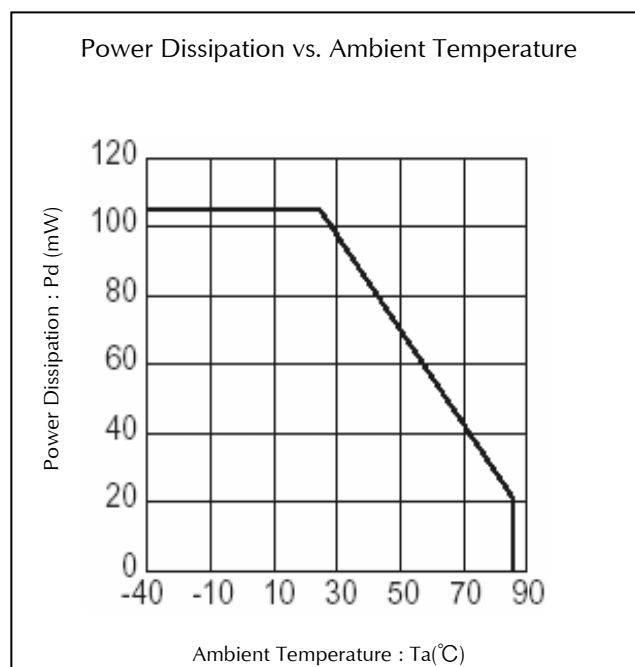
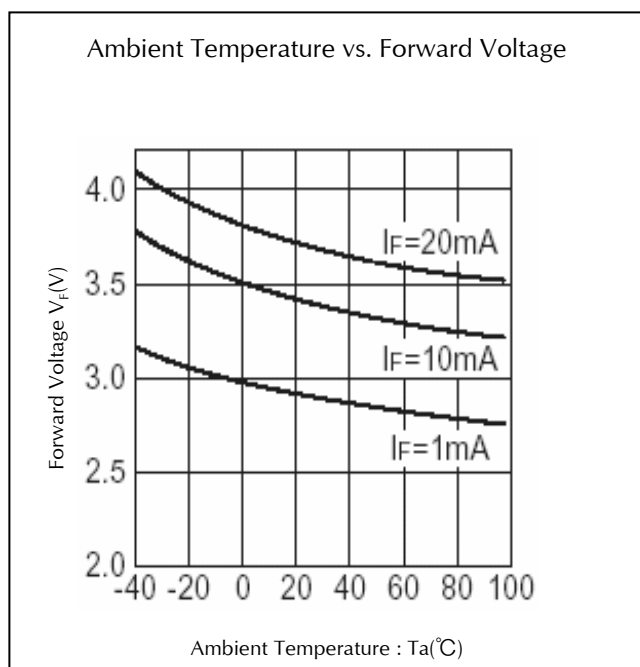
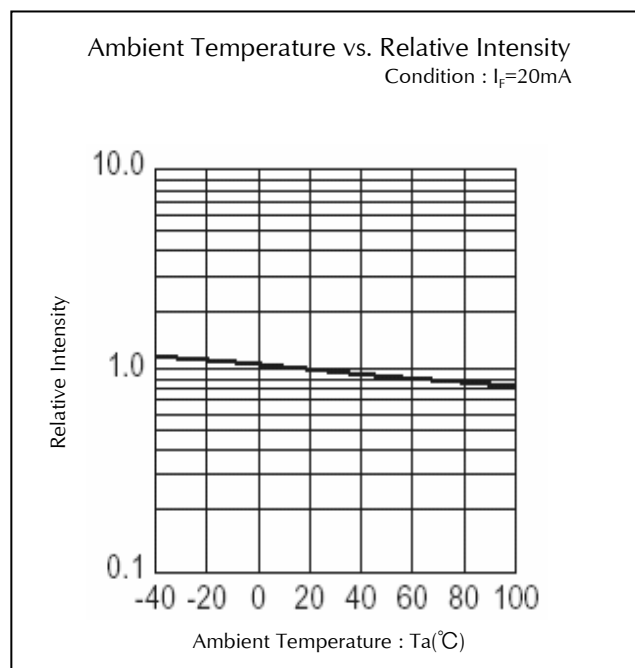
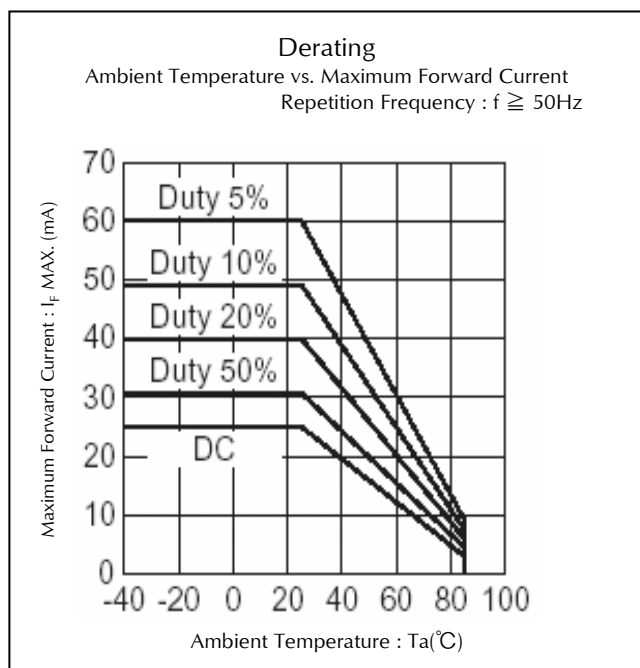
Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



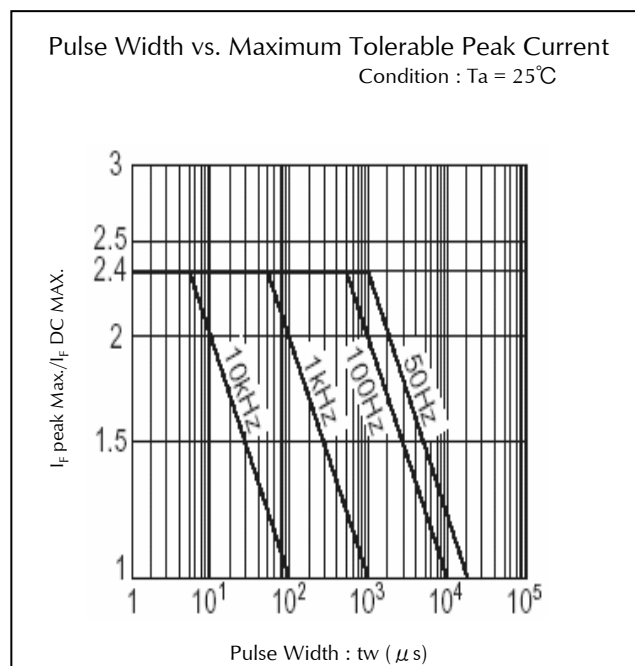
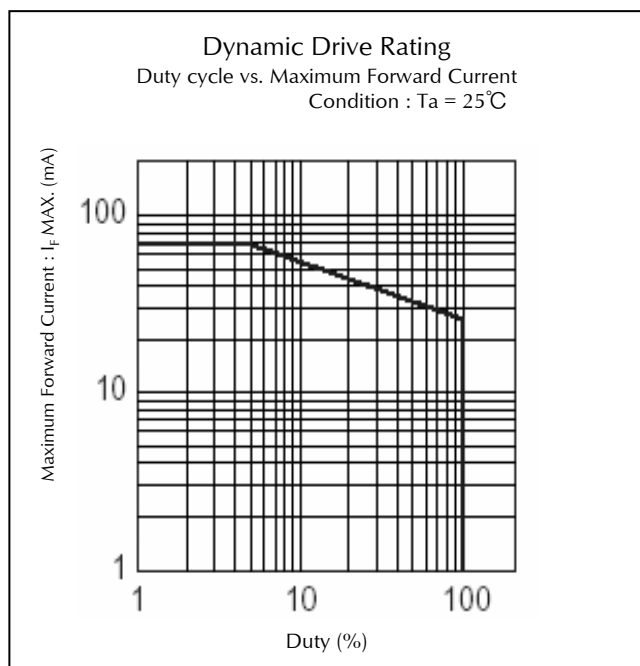
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(UG)

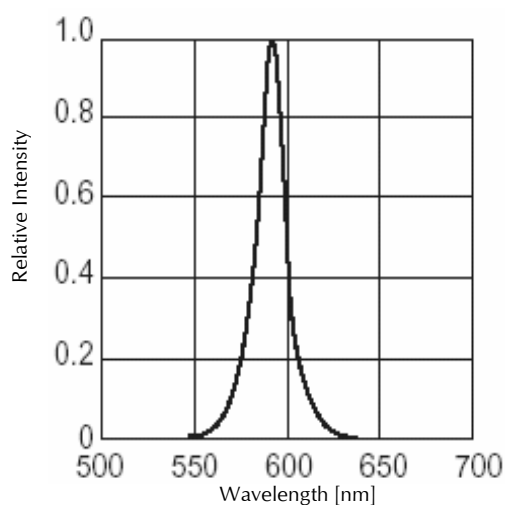


Technical Data(UG)



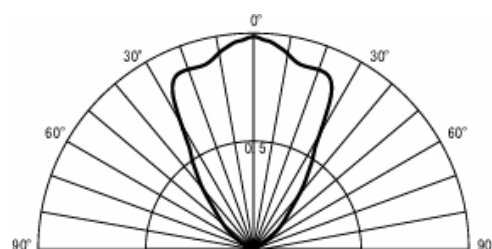
Technical Data(UY)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

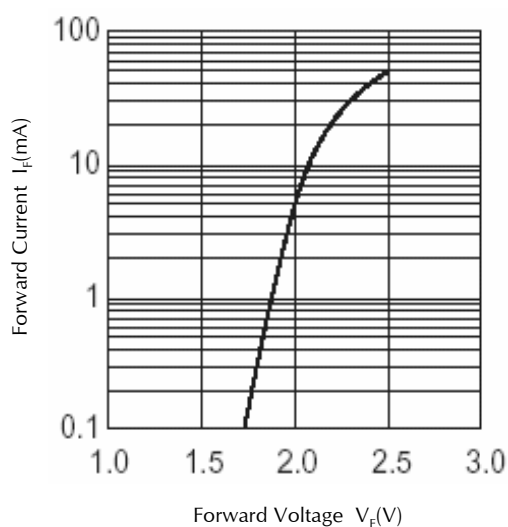


Spatial Distribution Example

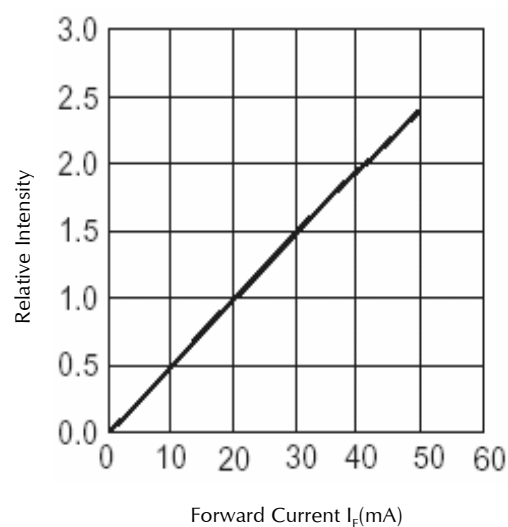
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



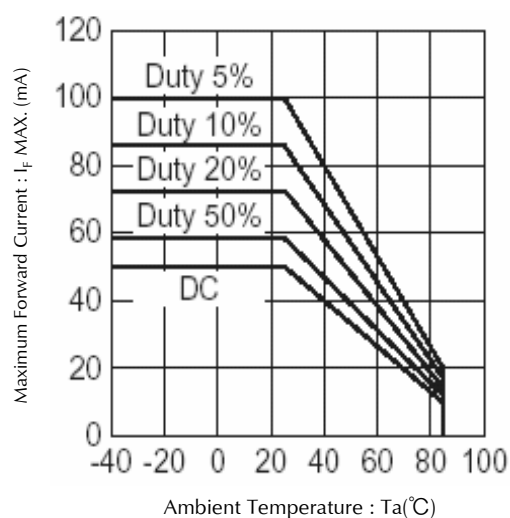
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(UY)

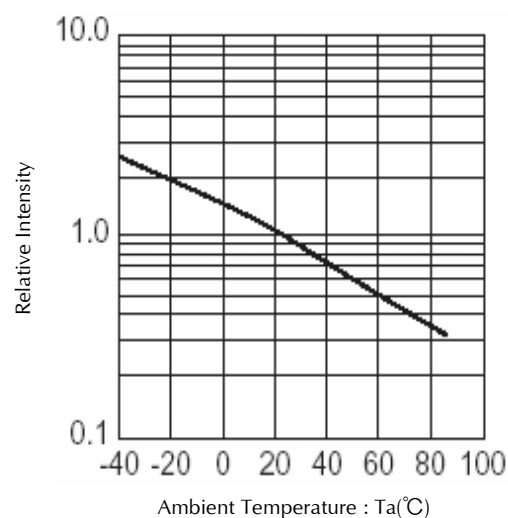
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

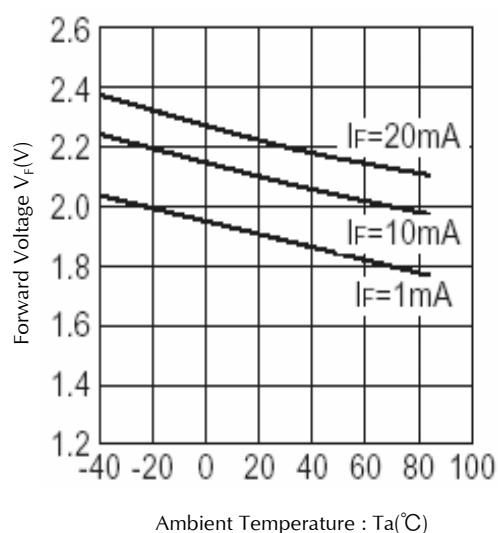


Ambient Temperature vs. Relative Intensity

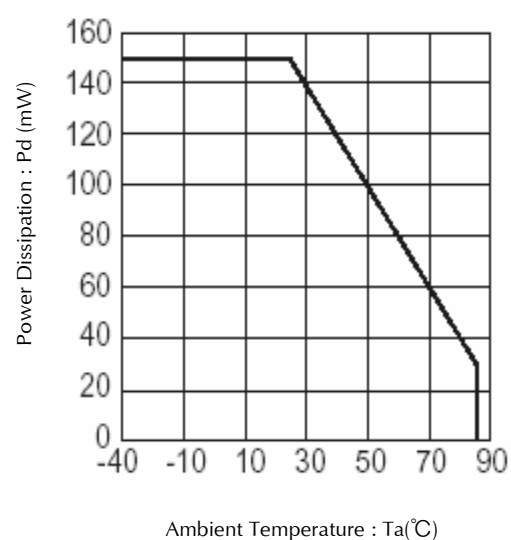
Condition : $I_F = 20\text{mA}$



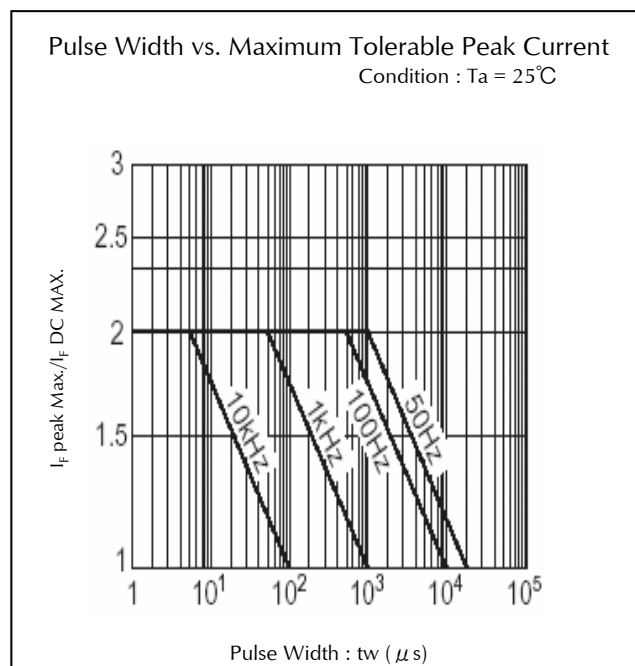
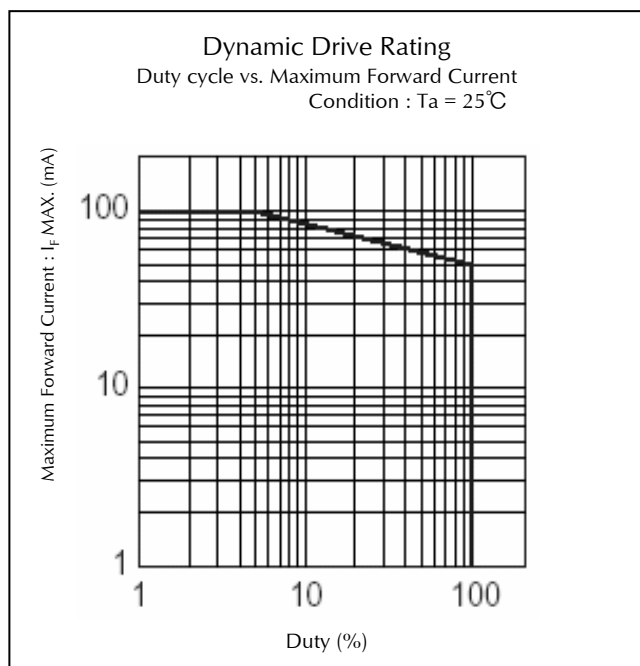
Ambient Temperature vs. Forward Voltage



Power Dissipation vs. Ambient Temperature

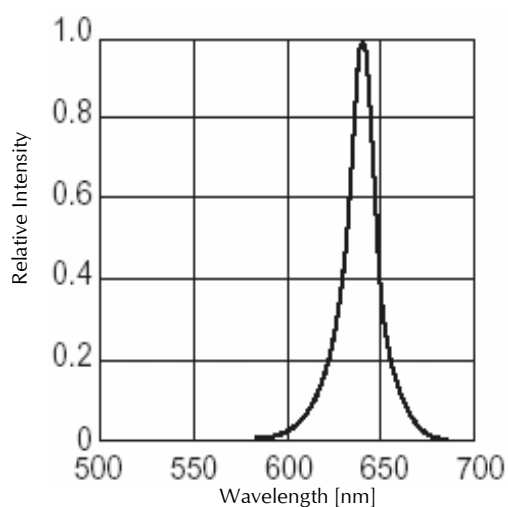


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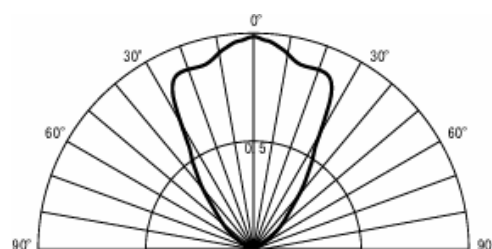
Technical Data(UR)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

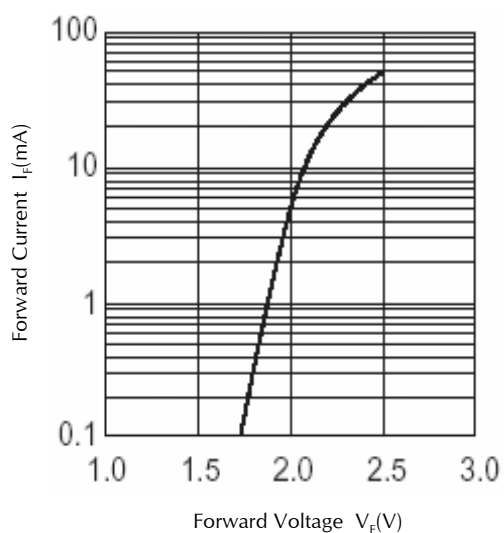


Spatial Distribution Example

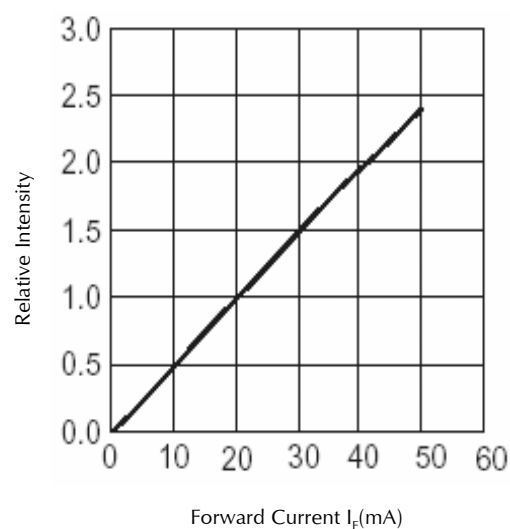
Condition : $T_a = 25^\circ\text{C}$



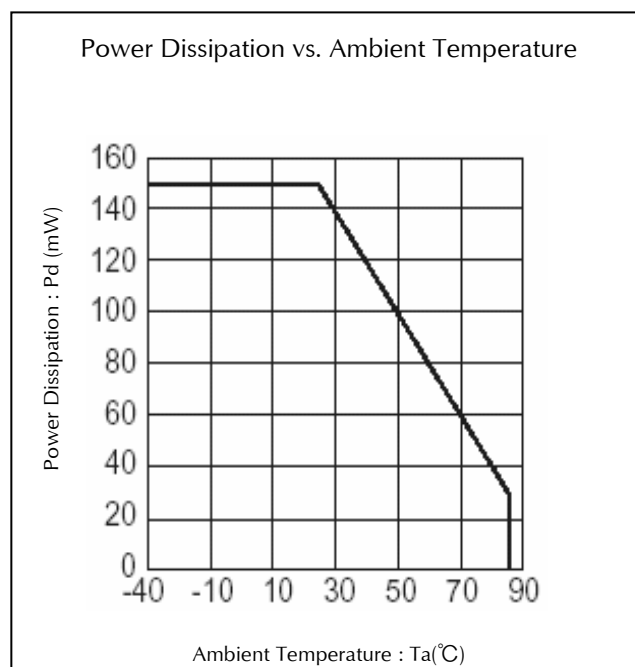
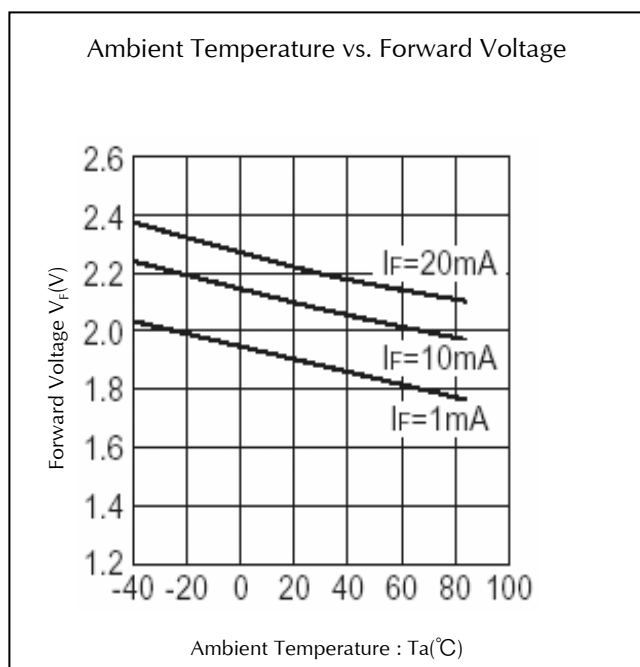
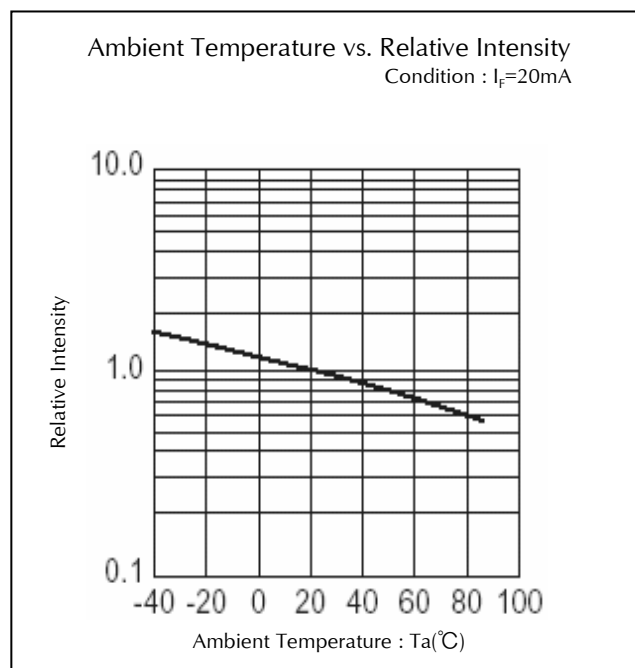
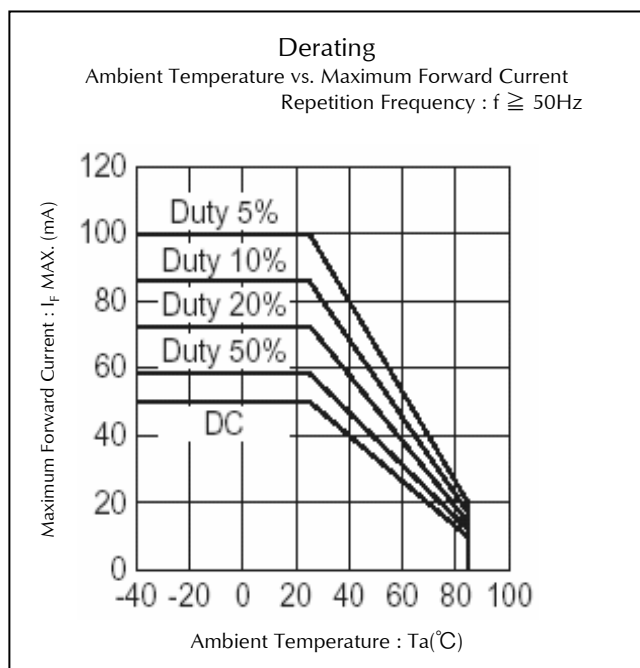
Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



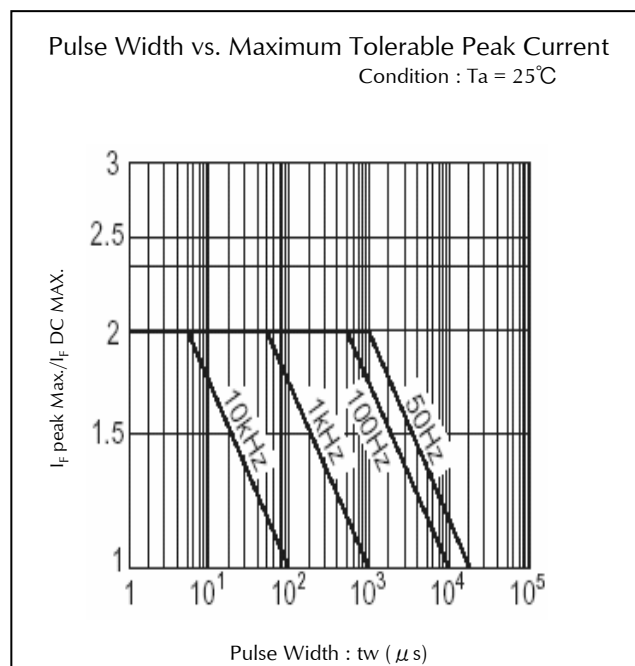
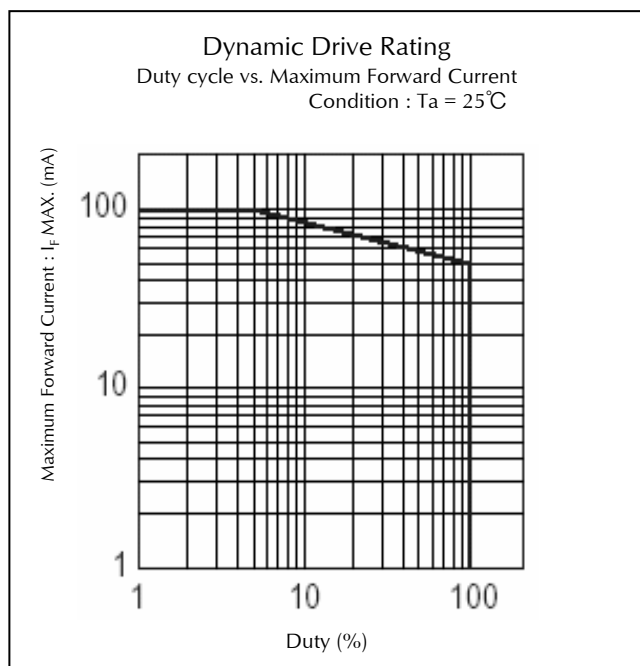
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(UR)

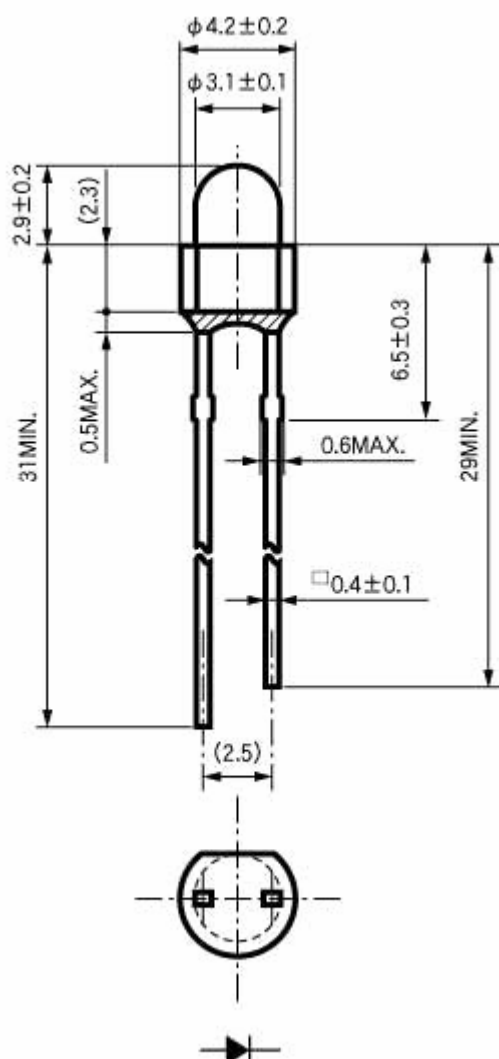


Technical Data(UR)



Package Dimensions

(Unit: mm)



TTW (Through The Wave) soldering Conditions

Pre-heating	100 °C	(MAX.)
Solder Bath Temp.	265°C	(MAX.)
Dipping Time	5 s	(MAX.)

- 1) The dip soldering process shall be 2 times maximum.
 - 2) The product shall be cooled to room temp. before the second dipping process.
- ※The detail is described to LED and Photodetector handling precautions of home page:
"Mounting through-hole Type Devices" and "Soldering", and use it after the confirmation, please.

Manual Soldering Conditions

Iron tip temp.	400°C	(MAX.)
Soldering time and frequency	3 s	(MAX.)
	2 times	(MAX.)

※The detail is described to LED and Photodetector handling precautions of home page:
"Mounting through-hole Type Devices" and "Soldering", and use it after the confirmation, please.

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25°C, If = Maximum Rated Current	1,000 h	0/25
Resistance to Soldering Heat	EIAJ ED-4701/300(302)	260±5°C, 1.6mm from package base	10s	0/25
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	5 cycles	0/25
Wet High Temp. Storage Life	EIAJ ED-4701/100(103)	Ta = 60±2°C, RH = 90±5%	1,000 h	0/25
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/25
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/25
Lead Tension	EIAJ ED-4701/400(401)	10N, 1time (□0.4 and Flat Package : 5N)	10s	0/10
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s ² (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V _F	If Value of each product Forward Voltage	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	Occurrence of notable decoloration, deformation and cracking

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